

Not Recommended for New Designs Use P/N: GMLB-100505-0600A-N8-RU

Products: Certifications:

Molded Power Chokes ISO9001

Multilayer Chip Inductors IATF16949

<u>Lan Transformer</u> ISO14001

RF Passive / Antennas QC080000

Automotive

US Office Contact Us

5406 Bolsa Ave., Huntington Beach, CA 92649 (714) 898-8377 www.maglayersusa.com info@maglayersusa.com

APPLICATION

GMLB chip beads can be used in a variety of electronic applications including:

- Computers and Computer Peripherals
- Cellular Communication Equipment
- Digital Cameras
- Digital Televisions
- Audio Equipment

FEATURES

The GMLB Series is Mag.Layers' line of high quality ferrite chip beads. Using the latest in multilayer technology, we have developed chip beads that are able to resolve all EMI/EMC issues. High quality, reliability, and versatility make the GMLB series chip beads suitable for all your design needs.

- High Reliability
 The monolithic inorganic materials used to construct GMLB chips restrain magnetic flux leakage thereby minimizing EMI concerns. GMLB chips are also extremely effective with unstable grounding.
- Small Chip-Shaped Design
 The chip-shaped design makes GMLB chip beads ideal for automatic mounting.
- High Soldering Heat Resistance
 High quality termination allows both flow and re-flow soldering methods to be applied.
- Sharp High Frequency Characteristics
 The GMLB high frequency chip series has sharp impedance characteristics, which make it suitable for high-speed signal lines.

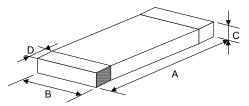
PRODUCT IDENTIFICATION

<u>G M L B</u>	-	100505	-	0030	<u>A</u> -	<u>N 8</u>	∐-R	U
①		2		3	4	(5)	6	

- ① Product Code
- ② Dimension Code
- 3 Impedance (at 100 MHz)
- Series Type
- ⑤ Design Code
- © Code for Special Specification



PRODUCT DIMENSION

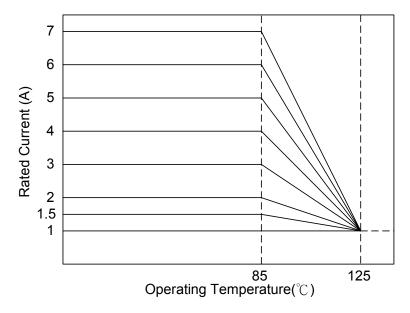


NOTE: Dimensions in mm

PRODUCT NO.	А	В	С	D
GMLB-100505	1.0±0.10	0.5±0.10	0.5±0.10	0.25±0.10
(0402)	(0.039±0.004)	(0.019±0.004)	(0.019±0.004)	(0.0095±0.004)

CURRENT DERATING

In operating temperatures exceeding +85°C, derating of current is necessary for chip ferrite beads for which rated current is 1.5A or over. Please apply the derating curve shown below according to the operating temperature.





ELECTRICAL REQUIREMENTS

Part Number	Impedance (Ω) at 100 MHz	R _{DC} (Ω) Max.	Rated Current (mA) Max.	Operating Temp. Range (℃)
GMLB-100505-0600A-N8-RU	600±25%	0.65	200	-55 ~ +125

Temperature rise should be less than 40[°]C for P-type and less than 25[°]C for other types when rated current is applied.

MEASURING METHOD / CONDITION

Test Instrument:

Z: Agilent 4291B Impedance Analyzer, Test Fixture: Agilent 16192

Osc. Level: 500mV

R_{DC}: Agilent 34401A

Test Condition:

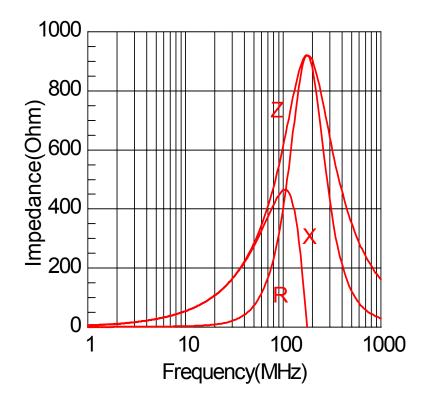
< Unless otherwise specified >

Temperature: 15°C to 35°C Humidity: 25% to 85% RH

< In case of doubt >

Temperature: 25°C ± 2°C Humidity: 60% to 70% RH

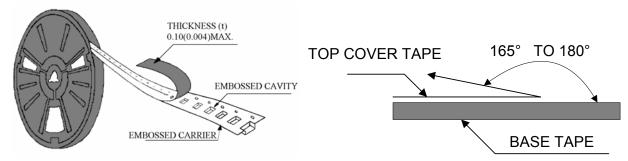
■ ELECTRICAL CHARACTERISTICS (T=25°C)





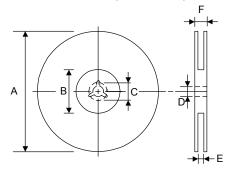
PACKAGING

Peel-off Force

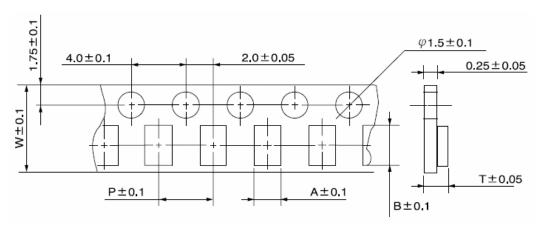


The force for peeling off cover tape is 10 grams in the arrow direction.

• **Dimension** (Unit: mm)



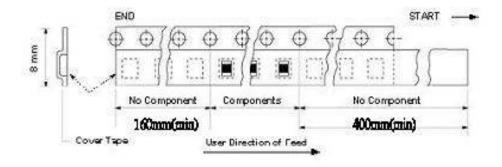
TYPE	Α	В	С	D	E	F
8 mm	178±1	60 +0.5 -0	-	13 ±0.2	9 ±0.5	12 ±0.5
12 mm	178±0.3	60 ±0.2	19.3 ±0.1	13.5 ±0.1	13.6 ±0.1	-



TYPE	SIZE	Α	В	W	Р	Т	CHIPS/REEL
GMLB	100505	0.6	1.1	8	2	1.0	10000

^{*:} For paper reels

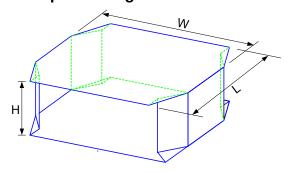




Taping Quantity

SERIES	1005
PCS/Reel	10000

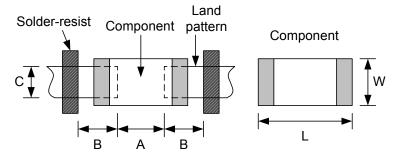
Tape Packing Case



No. of Reels	W	L	Н
2	18±0.5	18±0.5	2.4±0.2
3	18±0.5	18±0.5	3.6±0.2
4	18±0.5	18±0.5	4.8±0.2
5	18±0.5	18±0.5	6.0±0.2

Unit: cm

RECOMMENDED PCB LAYOUT



Unit: mm

Тур	е	1005
0:	L	1.0
Size	W	0.5
А		0.45~0.55
В		0.40~0.50
С		0.40~0.50



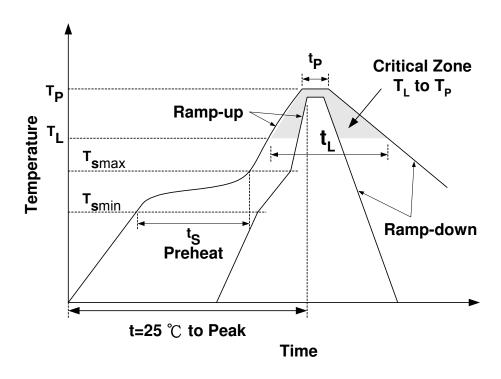
RELIABILTY TEST

 Mechanical Perfo 	rmance Test				
ITEM	SPECIFICATION	TEST CONDITION			
Solderability	More than 90% of the terminal electrode shall be covered with fresh solder.	Solder: 96.5Sn-3.0Ag-0.5Cu Solder Temperature: $245 \pm 5^{\circ}\text{C}$ Flux: Rosin Dip Time: 3 ± 1 Seconds			
Soldering Heat Resistance	The chip shall not crack. More than 75% of the terminal electrode shall be covered with solder.	Solder: 96.5Sn-3.0 Solder temperature Flux: Rosin Dip time: 10 ± 1 se	e : 260 ± 5°C		
	The terminal electrode shall not be broken off		W(KGF)	TIME (SEC)	
Terminal Strength	nor the ferrite damaged.	GMLB-100505	0.2	30 ± 5	
	No mechanical damage.	TYPE	A(MM)	P(KGF)	
Bending Strength	The ferrite shall not be damaged. R0.5 Chip A A	GMLB-100505	0.4	0.2	
 Climatic test 					
ITEM	SPECIFICATION	TEST CONDITION			
hermal Shock Impedance shall be within \pm 20% of the initial value.		Temperature cycle : -55°C~125°C for 30 minutes each. Total: 100 cycles.			
lumidity Resistance		Temperature : +60°C Humidity: 90% RH Applied current: rated current Time: 1000 ± 12 hours			
High Temperature Resistance		Temperature : 80°C Applied current: rated current Time: 1000 ± 12 hours			

- 1. Operating Temperature Range: -55 °C TO +125°C
- 2. Storage Condition: The temperature should be within -40°C∼85°C and humidity should be less than 75% RH. The product should be used within 6 months from the time of delivery.



RECOMMENDED REFLOW SOLDERING PROFILE



Profile Feature		Sn-Pb	Pb-Free	
	t _s	60~120 seconds	60~180 seconds	
Preheat	T _{smin}	100℃	150 ℃	
	T _{smax}	150℃	200℃	
Average ramp-up	rate (T _{smax} to T _P)	3°C/second max.	3°C/second max.	
Time main above	Temperature (T _L)	183℃	217℃	
Time main above	Time (t _L)	60~150 seconds	60~150 seconds	
Peak temperature	(T _P)	230 ℃	250~260 °ℂ	
Time within 5°C of temperature (t _P)	f actual peak	10 seconds	10 seconds	
Ramp-down rate		6°C/sec max.	6°C/sec max.	
Time 25 $℃$ to peal	k temperature	6 minutes max.	8 minutes max.	

NOTES

The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

